

Features

- Very high speed: 45 ns
- Temperature ranges
 - Industrial: -40 °C to +85 °C
 - Automotive-A: -40 °C to +85 °C
- Wide voltage range: 2.20 V to 3.60 V
- Pin compatible with CY62146DV30
- Ultra low standby power
 - Typical standby current: 1 μA
 - Maximum standby current: 7 μA
- Ultra low active power
 - Typical active current: 2 mA at f = 1 MHz
- Easy memory expansion with \overline{CE} and \overline{OE} features
- Automatic power down when deselected
- Complementary metal oxide semiconductor (CMOS) for optimum speed and power
- Available in a Pb-free 48-ball very fine-pitch ball grid array (VFBGA) and 44-pin TSOP II Packages

Functional Description

The CY62146EV30 is a high performance CMOS static RAM organized as 256K words by 16 bits. This device features an

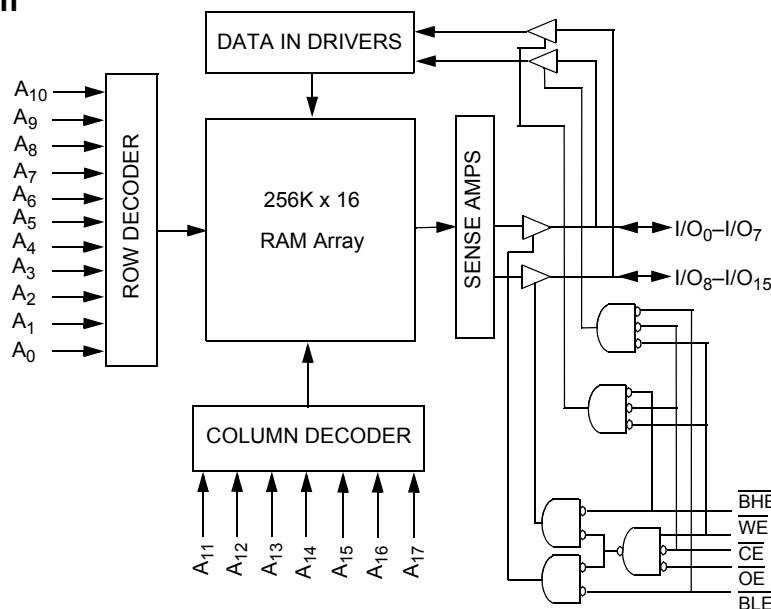
advanced circuit design designed to provide an ultra low active current. Ultra low active current is ideal for providing More Battery Life™ (MoBL®) in portable applications such as cellular telephones. The device also has an automatic power down feature that significantly reduces power consumption by 80 percent when addresses are not toggling. The device can also be put into standby mode reducing power consumption by more than 99 percent when deselected (\overline{CE} HIGH). The input and output pins (I/O_0 through I/O_{15}) are placed in a high impedance state when the device is deselected (\overline{CE} HIGH), outputs are disabled (\overline{OE} HIGH), both Byte High Enable and Byte Low Enable are disabled (\overline{BHE} , \overline{BLE} HIGH), or a write operation is in progress (\overline{CE} LOW and \overline{WE} LOW).

To write to the device, take Chip Enable (\overline{CE}) and Write Enable (\overline{WE}) input LOW. If Byte Low Enable (\overline{BLE}) is LOW, then data from I/O pins (I/O_0 through I/O_7) is written into the location specified on the address pins (A_0 through A_{17}). If Byte High Enable (\overline{BHE}) is LOW, then data from the I/O pins (I/O_8 through I/O_{15}) is written into the location specified on the address pins (A_0 through A_{17}).

To read from the device, take Chip Enable (\overline{CE}) and Output Enable (\overline{OE}) LOW while forcing the Write Enable (\overline{WE}) HIGH. If Byte Low Enable (\overline{BLE}) is LOW, then data from the memory location specified by the address pins appears on I/O_0 to I/O_7 . If Byte High Enable (\overline{BHE}) is LOW, then data from memory appears on I/O_8 to I/O_{15} . See the Truth Table on page 11 for a complete description of read and write modes.

For a complete list of related documentation, [click here](#).

Logic Block Diagram



Contents

Pin Configurations	3	Ordering Information	12
Product Portfolio	3	Ordering Code Definitions	12
Maximum Ratings	4	Package Diagrams	13
Operating Range	4	Acronyms	15
Electrical Characteristics	4	Document Conventions	15
Capacitance	5	Units of Measure	15
Thermal Resistance	5	Document History Page	16
AC Test Loads and Waveforms	5	Sales, Solutions, and Legal Information	18
Data Retention Characteristics	6	Worldwide Sales and Design Support	18
Data Retention Waveform	6	Products	18
Switching Characteristics	7	PSoC@Solutions	18
Switching Waveforms	8	Cypress Developer Community	18
Truth Table	11	Technical Support	18

Pin Configurations

Figure 1. 48-ball VFBGA pinout [1, 2]

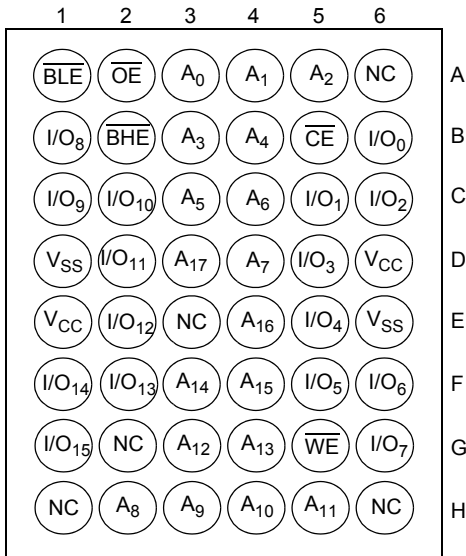
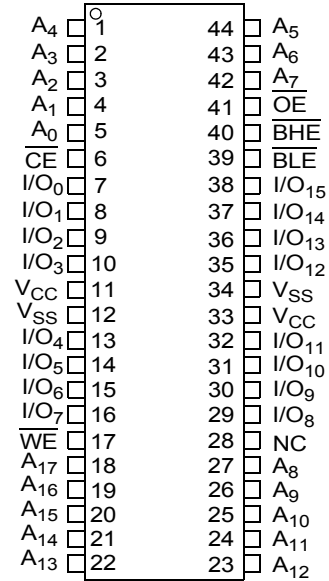


Figure 2. 44-pin TSOP II pinout [1]



Product Portfolio

Product	Range	V _{CC} Range (V)			Speed (ns)	Power Dissipation					
						Operating I _{CC} (mA)				Standby I _{SB2} (μA)	
		f = 1 MHz		f = f _{max}							
		Min	Typ ^[3]	Max		Typ ^[3]	Max	Typ ^[3]	Max	Typ ^[3]	Max
CY62146EV30LL	Industrial / Automotive-A	2.2	3.0	3.6	45	2	2.5	15	20	1	7

Notes

1. NC pins are not connected on the die.
2. Pins H1, G2, and H6 in the BGA package are address expansion pins for 8Mb, 16Mb and 32Mb respectively.
3. Typical values are included for reference only and are not guaranteed or tested. Typical values are measured at V_{CC} = V_{CC(typ)}, T_A = 25 °C.

Maximum Ratings

Exceeding the maximum ratings may impair the useful life of the device. These user guidelines are not tested.

Storage temperature	-65 °C to + 150 °C
Ambient temperature with power applied	-55 °C to + 125 °C
Supply voltage to ground potential	-0.3 V to + 3.9 V ($V_{CCmax} + 0.3$ V)
DC voltage applied to outputs in High-Z state ^[4, 5]	-0.3 V to 3.9 V ($V_{CCmax} + 0.3$ V)

DC input voltage ^[4, 5]	-0.3 V to 3.9 V ($V_{CCmax} + 0.3$ V)
Output current into outputs (LOW)	20 mA
Static Discharge Voltage (per MIL-STD-883, Method 3015)	>2001 V
Latch-up Current	>200 mA

Operating Range

Device	Range	Ambient Temperature	V_{CC} ^[6]
CY62146EV30	Industrial / Automotive-A	-40 °C to +85 °C	2.2 V to 3.6 V

Electrical Characteristics

Over the Operating Range

Parameter	Description	Test Conditions	45 ns (Ind!l/Auto-A)			Unit
			Min	Typ ^[7]	Max	
V_{OH}	Output high voltage	$I_{OH} = -0.1$ mA	2.0	-	-	V
		$I_{OH} = -1.0$ mA, $V_{CC} \geq 2.70$ V	2.4	-	-	V
V_{OL}	Output low voltage	$I_{OL} = 0.1$ mA	-	-	0.4	V
		$I_{OL} = 2.1$ mA, $V_{CC} \geq 2.70$ V	-	-	0.4	V
V_{IH}	Input high voltage	$V_{CC} = 2.2$ V to 2.7 V	1.8	-	$V_{CC} + 0.3$	V
		$V_{CC} = 2.7$ V to 3.6 V	2.2	-	$V_{CC} + 0.3$	V
V_{IL}	Input LOW Voltage	$V_{CC} = 2.2$ V to 2.7 V	-0.3	-	0.6	V
		$V_{CC} = 2.7$ V to 3.6 V	-0.3	-	0.8	V
I_{IX}	Input leakage current	$GND \leq V_I \leq V_{CC}$	-1	-	+1	μ A
I_{OZ}	Output leakage current	$GND \leq V_O \leq V_{CC}$, Output disabled	-1	-	+1	μ A
I_{CC}	V_{CC} operating supply current	$f = f_{max} = 1/t_{RC}$	-	15	20	mA
		$f = 1$ MHz		2	2.5	
I_{SB1}	Automatic CE power down current – CMOS inputs	$\overline{CE} > V_{CC} - 0.2$ V, $V_{IN} > V_{CC} - 0.2$ V or $V_{IN} < 0.2$ V, $f = f_{max}$ (Address and data only), $f = 0$ (\overline{OE} , \overline{BHE} , \overline{BLE} and \overline{WE}), $V_{CC} = 3.60$ V	-	1	7	μ A
I_{SB2} ^[8]	Automatic CE power down current – CMOS inputs	$\overline{CE} \geq V_{CC} - 0.2$ V, $V_{IN} \geq V_{CC} - 0.2$ V or $V_{IN} \leq 0.2$ V, $f = 0$, $V_{CC} = 3.60$ V	-	1	7	μ A

Notes

- $V_{IL(min)}$ = -2.0 V for pulse durations less than 20 ns.
- $V_{IH(max)}$ = $V_{CC} + 0.75$ V for pulse durations less than 20 ns.
- Full device AC operation assumes a minimum of 100 μ s ramp time from 0 to $V_{CC(min)}$ and 200 μ s wait time after V_{CC} stabilization.
- Typical values are included for reference only and are not guaranteed or tested. Typical values are measured at $V_{CC} = V_{CC(typ)}$, $T_A = 25$ °C.
- Chip enable (\overline{CE}) and byte enables (\overline{BHE} and \overline{BLE}) need to be tied to CMOS levels to meet the I_{SB1} / I_{SB2} / I_{CCDR} spec. Other inputs can be left floating.

Capacitance

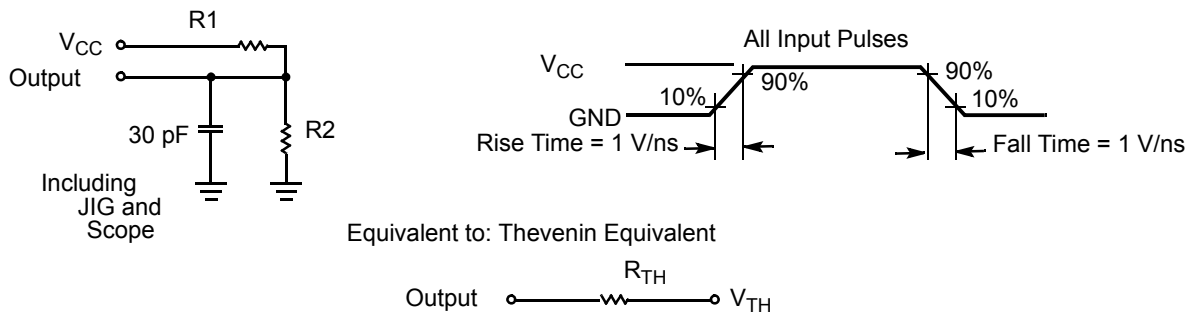
Parameter ^[9]	Description	Test Conditions	Max	Unit
C _{IN}	Input capacitance	T _A = 25 °C, f = 1 MHz, V _{CC} = V _{CC(typ)}	10	pF
C _{OUT}	Output capacitance		10	pF

Thermal Resistance

Parameter ^[9]	Description	Test Conditions	VFBGA	TSOP II	Unit
Θ _{JA}	Thermal resistance (junction to ambient)	Still air, soldered on a 3 × 4.5 inch, four-layer printed circuit board	42.10	55.52	°C/W
Θ _{JC}	Thermal resistance (junction to case)		23.45	16.03	°C/W

AC Test Loads and Waveforms

Figure 3. AC Test Loads and Waveforms



Parameters	2.50 V	3.0 V	Unit
R1	16667	1103	Ω
R2	15385	1554	Ω
R _{TH}	8000	645	Ω
V _{TH}	1.20	1.75	V

Note

9. Tested initially and after any design or process changes that may affect these parameters.

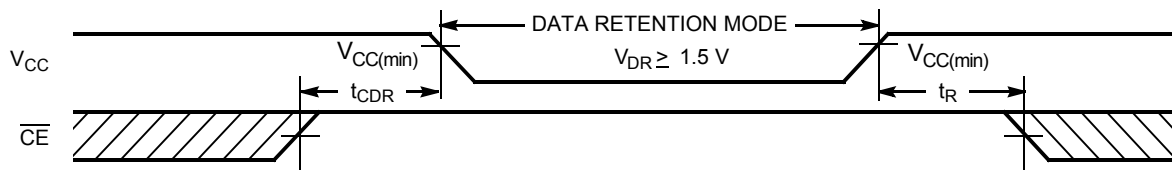
Data Retention Characteristics

Over the Operating Range

Parameter	Description	Conditions	Min	Typ ^[10]	Max	Unit
V_{DR}	V_{CC} for data retention		1.5	–	–	V
I_{CCDR} ^[11]	Data retention current	$V_{CC} = 1.5\text{ V}$, $\overline{CE} \geq V_{CC} - 0.2\text{ V}$, $V_{IN} \geq V_{CC} - 0.2\text{ V}$ or $V_{IN} \leq 0.2\text{ V}$	–	0.8	7	μA
t_{CDR} ^[12]	Chip deselect to data retention time	–	0	–	–	ns
t_R ^[13]	Operation recovery time	–	45	–	–	ns

Data Retention Waveform

Figure 4. Data Retention Waveform



Notes

10. Typical values are included for reference only and are not guaranteed or tested. Typical values are measured at $V_{CC} = V_{CC(\text{typ})}$, $T_A = 25\text{ }^\circ\text{C}$.
11. Chip enable (CE) and byte enables (BHE and BLE) need to be tied to CMOS levels to meet the $I_{SB1}/I_{SB2}/I_{CCDR}$ spec. Other inputs can be left floating.
12. Tested initially and after any design or process changes that may affect these parameters.
13. Full device operation requires linear V_{CC} ramp from V_{DR} to $V_{CC(\text{min})} \geq 100\text{ }\mu\text{s}$ or stable at $V_{CC(\text{min})} \geq 100\text{ }\mu\text{s}$.

Switching Characteristics

Over the Operating Range

Parameter ^[14, 15]	Description	45 ns (Industrial / Automotive-A)		Unit
		Min	Max	
Read Cycle				
t _{RC}	Read cycle time	45	–	ns
t _{AA}	Address to data valid	–	45	ns
t _{OHA}	Data hold from address change	10	–	ns
t _{ACE}	\overline{CE} LOW to data valid	–	45	ns
t _{DOE}	\overline{OE} LOW to data valid	–	22	ns
t _{LZOE}	\overline{OE} LOW to Low-Z ^[16]	5	–	ns
t _{HZOE}	\overline{OE} HIGH to High-Z ^[16, 17]	–	18	ns
t _{LZCE}	\overline{CE} LOW to Low-Z ^[16]	10	–	ns
t _{HZCE}	\overline{CE} HIGH to High-Z ^[16, 17]	–	18	ns
t _{PU}	\overline{CE} LOW to power up	0	–	ns
t _{PD}	\overline{CE} HIGH to power down	–	45	ns
t _{DBE}	$\overline{BLE} / \overline{BHE}$ LOW to data valid	–	22	ns
t _{LZBE}	$\overline{BLE} / \overline{BHE}$ LOW to Low-Z ^[16]	5	–	ns
t _{HZBE}	$\overline{BLE} / \overline{BHE}$ HIGH to High-Z ^[16, 17]	–	18	ns
Write Cycle ^[18, 19]				
t _{WC}	Write cycle time	45	–	ns
t _{SCE}	\overline{CE} LOW to write end	35	–	ns
t _{AW}	Address setup to write end	35	–	ns
t _{HA}	Address hold from write end	0	–	ns
t _{SA}	Address setup to write start	0	–	ns
t _{PWE}	\overline{WE} pulse width	35	–	ns
t _{BW}	$\overline{BLE} / \overline{BHE}$ LOW to write end	35	–	ns
t _{SD}	Data setup to write end	25	–	ns
t _{HD}	Data hold from write end	0	–	ns
t _{HZWE}	\overline{WE} LOW to High-Z ^[16, 17]	–	18	ns
t _{LZWE}	\overline{WE} HIGH to Low-Z ^[16]	10	–	ns

Notes

- Test conditions for all parameters other than tri-state parameters assume signal transition time of 3 ns (1 V/ns) or less, timing reference levels of $V_{CC(typ)}/2$, input pulse levels of 0 to $V_{CC(typ)}$, and output loading of the specified I_{OL}/I_{OH} as shown in the [Figure 3 on page 5](#).
- In an earlier revision of this device, under a specific application condition, READ and WRITE operations were limited to switching of the byte enable and/or chip enable signals as described in the Application Notes [AN13842](#) and [AN66311](#). However, the issue has been fixed and in production now, and hence, these Application Notes are no longer applicable. They are available for download on our website as they contain information on the date code of the parts, beyond which the fix has been in production.
- At any given temperature and voltage condition, t_{HZCE} is less than t_{LZCE} , t_{HZBE} is less than t_{LZBE} , t_{HZOE} is less than t_{LZOE} , and t_{HZWE} is less than t_{LZWE} for any given device.
- t_{HZOE} , t_{HZCE} , t_{HZBE} , and t_{HZWE} transitions are measured when the outputs enter a high impedance state.
- The internal write time of the memory is defined by the overlap of \overline{WE} , $\overline{CE} = V_{IL}$, \overline{BHE} and/or $\overline{BLE} = V_{IL}$. All signals must be ACTIVE to initiate a write and any of these signals can terminate a write by going INACTIVE. The data input setup and hold timing must be referenced to the edge of the signal that terminates the write.
- The minimum write pulse width for Write Cycle No. 3 (\overline{WE} controlled, \overline{OE} LOW) should be sum of t_{HZWE} and t_{SD} .

Switching Waveforms

Figure 5. Read Cycle 1 (Address Transition Controlled) [20, 21]

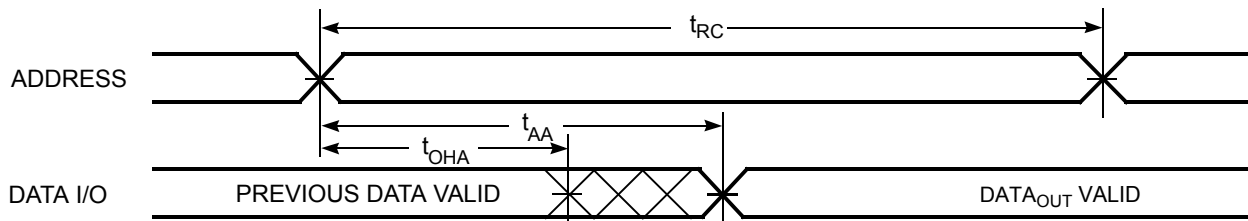
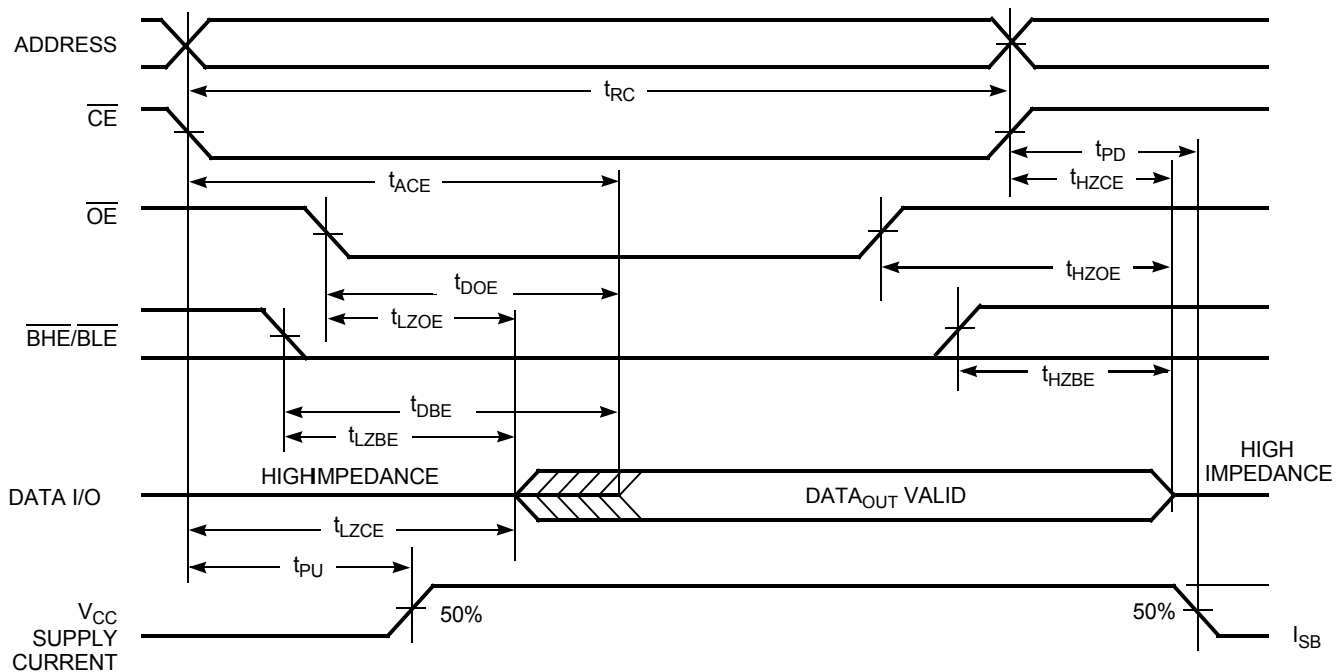


Figure 6. Read Cycle No. 2 (\overline{OE} Controlled) [21, 22]



Notes

- 20. The device is continuously selected. \overline{OE} , $\overline{CE} = V_{IL}$, \overline{BHE} and/or $\overline{BLE} = V_{IL}$.
- 21. \overline{WE} is HIGH for read cycle.
- 22. Address valid before or similar to \overline{CE} and \overline{BHE} , \overline{BLE} transition LOW.

Switching Waveforms (continued)

Figure 7. Write Cycle No. 1 (\overline{WE} Controlled) [23, 24, 25]

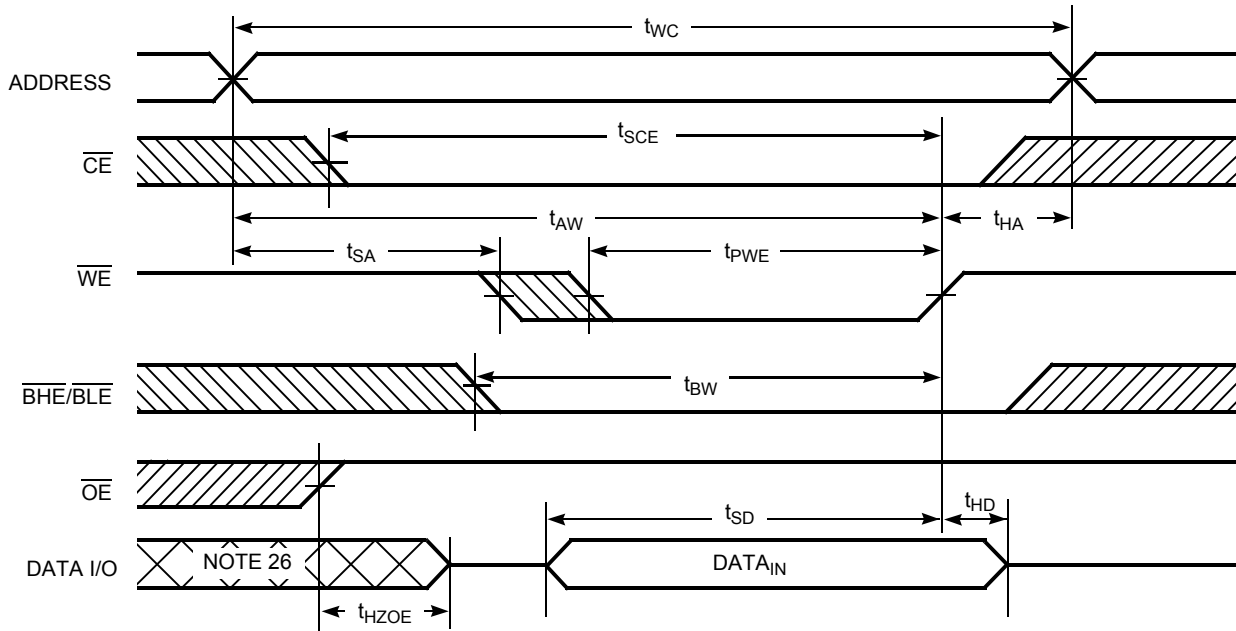
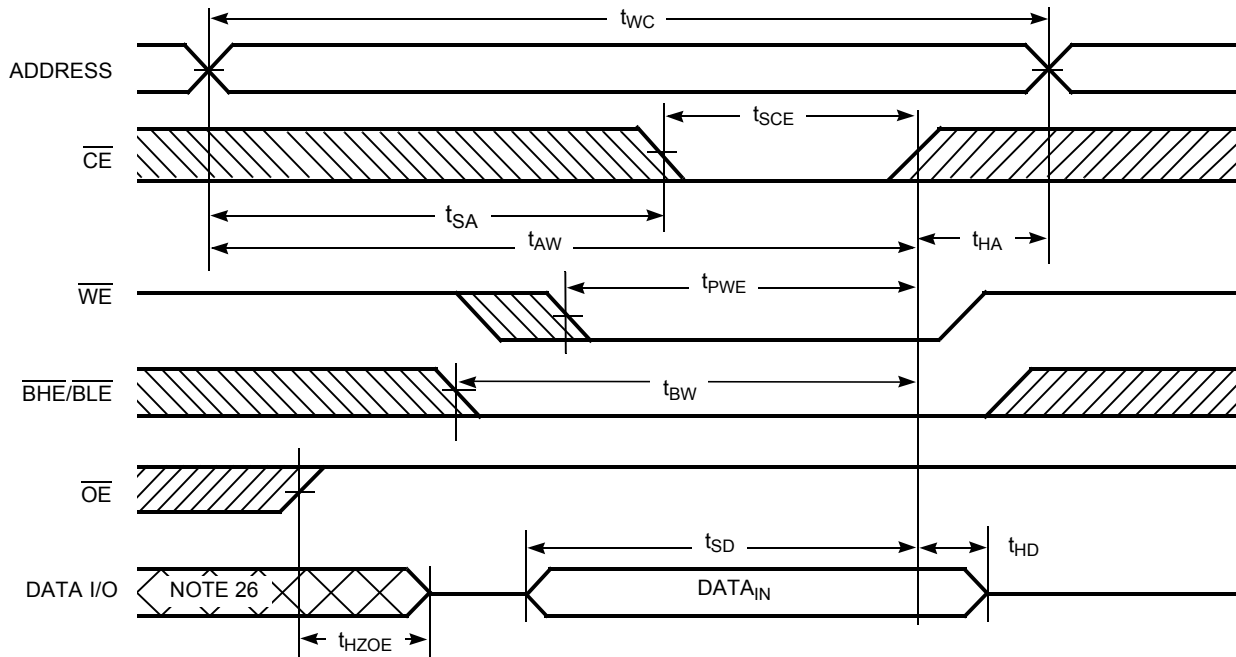


Figure 8. Write Cycle No. 2 (\overline{CE} Controlled) [23, 24, 25]



Notes

- 23. The internal write time of the memory is defined by the overlap of \overline{WE} , $\overline{CE} = V_{IL}$, \overline{BHE} and/or $\overline{BLE} = V_{IL}$. All signals must be ACTIVE to initiate a write and any of these signals can terminate a write by going INACTIVE. The data input setup and hold timing must be referenced to the edge of the signal that terminates the write.
- 24. Data I/O is high impedance if $\overline{OE} = V_{IH}$.
- 25. If \overline{CE} goes HIGH simultaneously with $\overline{WE} = V_{IH}$, the output remains in a high impedance state.
- 26. During this period, the I/Os are in output state and input signals must not be applied.

Switching Waveforms (continued)

Figure 9. Write Cycle No. 3 (\overline{WE} Controlled, \overline{OE} LOW) [27, 28]

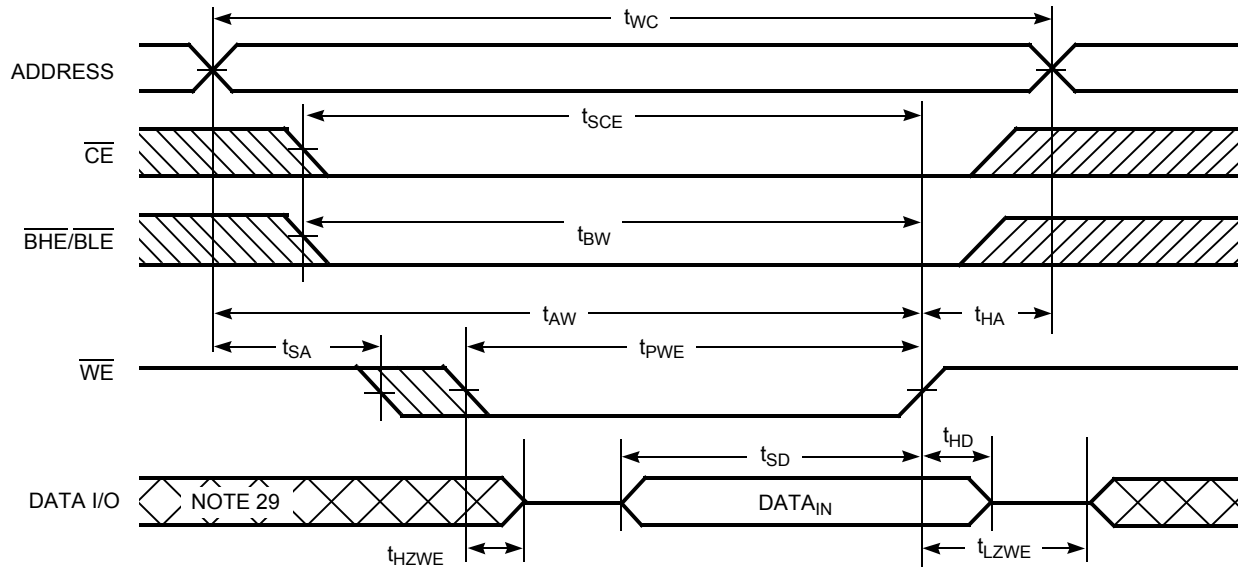
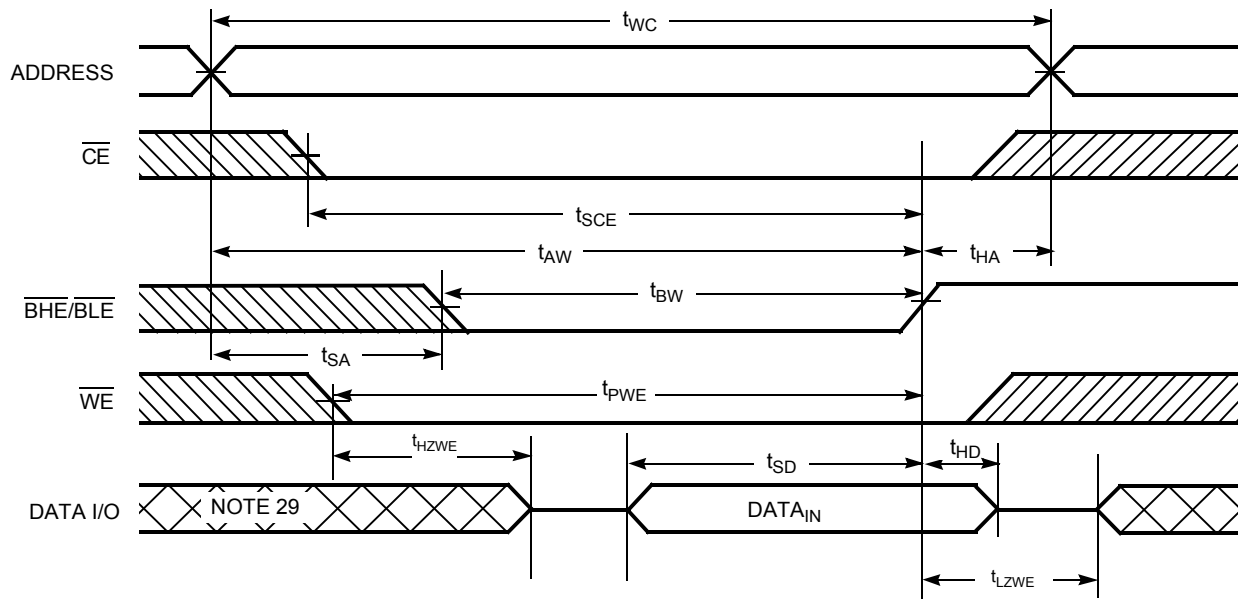


Figure 10. Write Cycle No. 4 ($\overline{BHE}/\overline{BLE}$ Controlled, \overline{OE} LOW) [27]



Notes

- 27. If \overline{CE} goes HIGH simultaneously with $\overline{WE} = V_{IH}$, the output remains in a high impedance state.
- 28. The minimum write pulse width for Write Cycle No. 3 (\overline{WE} Controlled, \overline{OE} LOW) should be sum of t_{HZWE} and t_{SD} .
- 29. During this period, the I/Os are in output state and input signals must not be applied.

Truth Table

CE ^[30]	WE	OE	BHE	BLE	Inputs/Outputs	Mode	Power
H	X	X	X	X	High-Z	Deselect/power-down	Standby (I _{SB})
L	X	X	H	H	High-Z	Output disabled	Active (I _{CC})
L	H	L	L	L	Data out (I/O ₀ –I/O ₁₅)	Read	Active (I _{CC})
L	H	L	H	L	Data out (I/O ₀ –I/O ₇); I/O ₈ –I/O ₁₅ in High-Z	Read	Active (I _{CC})
L	H	L	L	H	Data out (I/O ₈ –I/O ₁₅); I/O ₀ –I/O ₇ in High-Z	Read	Active (I _{CC})
L	H	H	L	L	High-Z	Output disabled	Active (I _{CC})
L	H	H	H	L	High-Z	Output disabled	Active (I _{CC})
L	H	H	L	H	High-Z	Output disabled	Active (I _{CC})
L	L	X	L	L	Data in (I/O ₀ –I/O ₁₅)	Write	Active (I _{CC})
L	L	X	H	L	Data in (I/O ₀ –I/O ₇); I/O ₈ –I/O ₁₅ in High-Z	Write	Active (I _{CC})
L	L	X	L	H	Data in (I/O ₈ –I/O ₁₅); I/O ₀ –I/O ₇ in High-Z	Write	Active (I _{CC})

Note

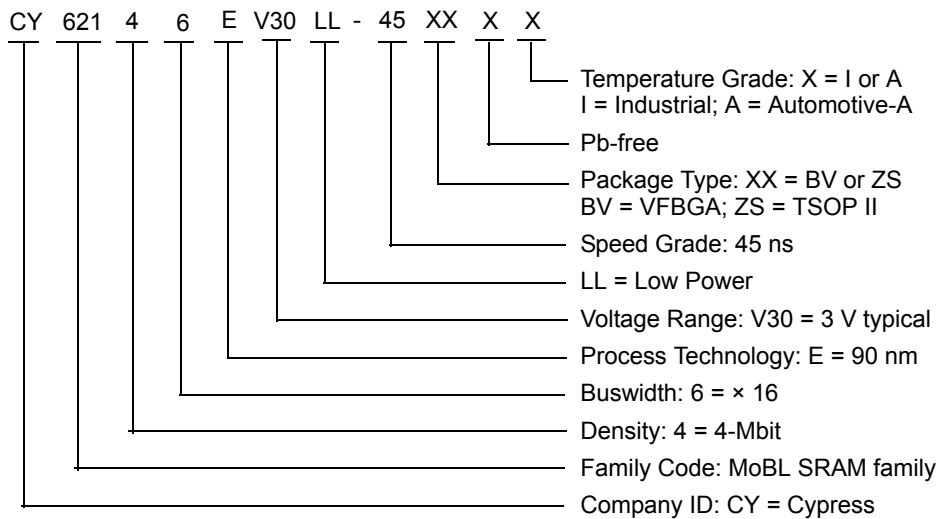
30. Chip enable must be at CMOS levels (not floating). Intermediate voltage levels on this pin is not permitted.

Ordering Information

Speed (ns)	Ordering Code	Package Diagram	Package Type	Operating Range
45	CY62146EV30LL-45BVXI	51-85150	48-ball VFBGA (Pb-free)	Industrial
	CY62146EV30LL-45ZSXI	51-85087	44-pin TSOP II (Pb-free)	
	CY62146EV30LL-45ZSXA	51-85087	44-pin TSOP II (Pb-free)	Automotive-A

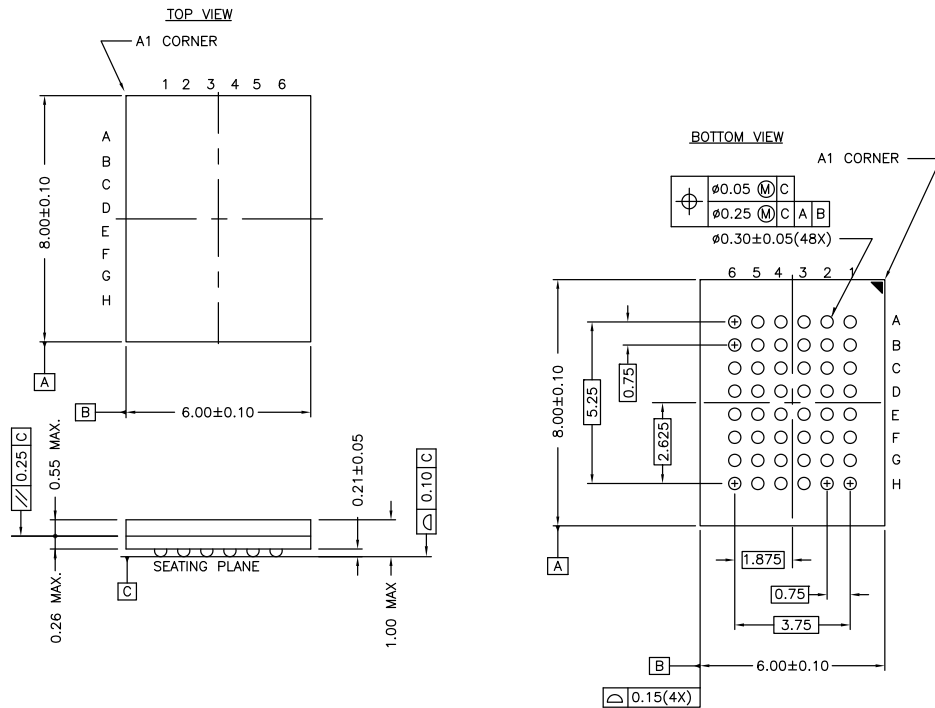
Please contact your local Cypress sales representative for availability of other parts

Ordering Code Definitions



Package Diagrams

Figure 11. 48-ball VFBGA (6 × 8 × 1.0 mm) BV48/BZ48 Package Outline, 51-85150

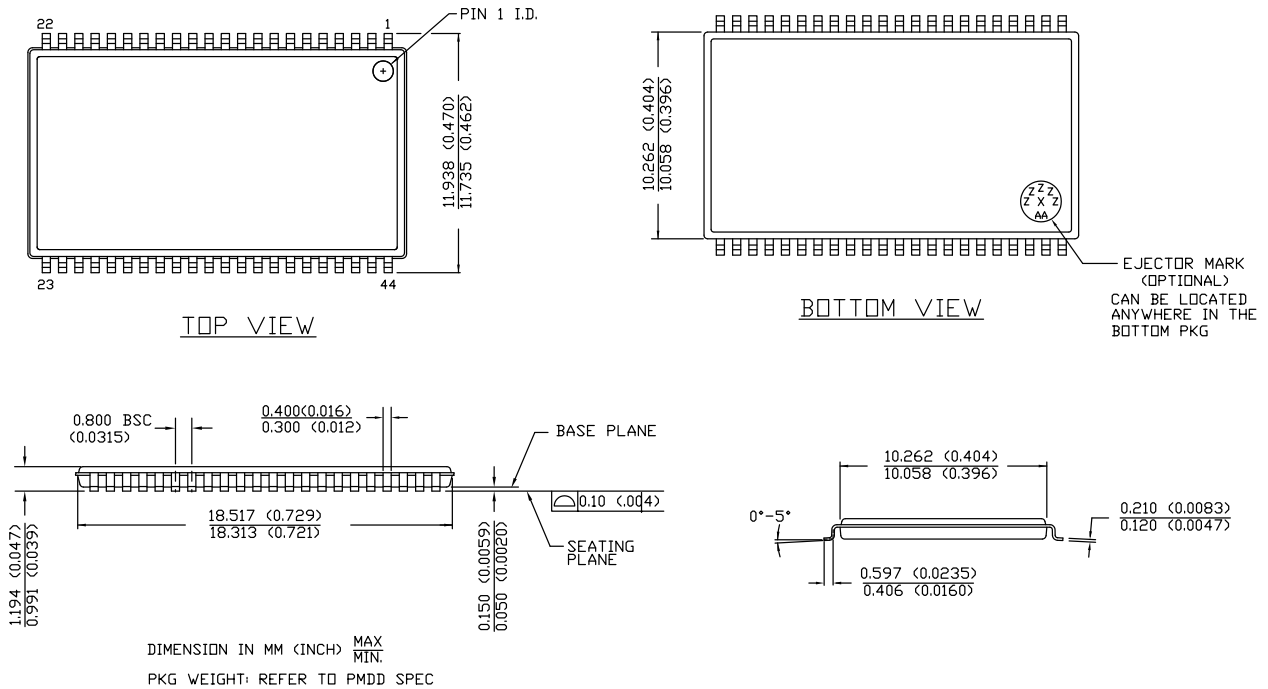


NOTE:
 PACKAGE WEIGHT: See Cypress Package Material Declaration Datasheet (PMDD) posted on the Cypress web.

51-85150 *H

Package Diagrams (continued)

Figure 12. 44-pin TSOP Z44-II Package Outline, 51-85087



51-85087 *E

Acronyms

Acronym	Description
$\overline{\text{BHE}}$	Byte High Enable
$\overline{\text{BLE}}$	Byte Low Enable
CMOS	Complementary Metal Oxide Semiconductor
$\overline{\text{CE}}$	Chip Enable
I/O	Input/Output
$\overline{\text{OE}}$	Output Enable
SRAM	Static Random Access Memory
TSOP	Thin Small Outline Package
VFBGA	Very Fine-Pitch Ball Grid Array
$\overline{\text{WE}}$	Write Enable

Document Conventions

Units of Measure

Symbol	Unit of Measure
°C	degree Celsius
MHz	megahertz
μA	microampere
mA	milliampere
ns	nanosecond
Ω	ohm
pF	picofarad
V	volt
W	watt

Document History Page

Document Title: CY62146EV30 MoBL [®] , 4-Mbit (256K × 16) Static RAM Document Number: 38-05567				
Rev.	ECN No.	Orig. of Change	Submission Date	Description of Change
**	223225	AJU	See ECN	New data sheet.
*A	247373	SYT	See ECN	<p>Changed status from Advance Information to Preliminary. Moved Product Portfolio to Page 2 Changed V_{CC} stabilization time in footnote #8 from 100 μs to 200 μs Removed Footnote #14(t_{LZBE}) from Previous revision Changed I_{CCDR} from 2.0 μA to 2.5 μA Changed typo in Data Retention Characteristics (t_R) from 100 μs to t_{RC} ns Changed t_{OHA} from 6 ns to 10 ns for both 35 ns and 45 ns Speed Bin Changed t_{HZOE}, t_{HZBE}, t_{HZWE} from 12 to 15 ns for 35 ns Speed Bin and 15 to 18 ns for 45 ns Speed Bin Changed t_{SCE} and t_{BW} from 25 to 30 ns for 35 ns Speed Bin and 40 to 35 ns for 45 ns Speed Bin Changed t_{HZCE} from 12 to 18 ns for 35 ns Speed Bin and 15 to 22 ns for 45 ns Speed Bin Changed t_{SD} from 15 to 18 ns for 35 ns Speed Bin and 20 to 22 ns for 45 ns Speed Bin Changed t_{DOE} from 15 to 18 ns for 35 ns Speed Bin Changed t_{DBE} from 15 to 18 ns for 35 ns Speed Bin Changed Ordering Information to include Pb-Free Packages</p>
*B	414807	ZSD	See ECN	<p>Changed status from Preliminary to Final. Changed the address of Cypress Semiconductor Corporation on Page #1 from "3901 North First Street" to "198 Champion Court" Removed 35ns Speed Bin Removed "L" version of CY62146EV30 Changed ball E3 from DNU to NC Removed the redundant foot note on DNU. Changed I_{CC} (Max) value from 2 mA to 2.5 mA and I_{CC} (Typ) value from 1.5 mA to 2 mA at f=1 MHz Changed I_{CC} (Typ) value from 12 mA to 15 mA at f = f_{max} Changed I_{SB1} and I_{SB2} Typ values from 0.7 μA to 1 μA and Max values from 2.5 μA to 7 μA. Changed the AC test load capacitance from 50pF to 30pF on Page# 4 Changed I_{CCDR} from 2.5 μA to 7 μA. Added I_{CCDR} typical value. Changed t_{LZOE} from 3 ns to 5 ns Changed t_{LZCE} and t_{LZWE} from 6 ns to 10 ns Changed t_{LZBE} from 6 ns to 5 ns Changed t_{HZCE} from 22 ns to 18 ns Changed t_{PWE} from 30 ns to 35 ns. Changed t_{SD} from 22 ns to 25 ns. Updated the package diagram 48-ball VFBGA from *B to *D Updated the ordering information table and replaced the Package Name column with Package Diagram.</p>
*C	925501	VKN	See ECN	<p>Added footnote #8 related to I_{SB2} and I_{CCDR} Added footnote #12 related AC timing parameters</p>
*D	2678796	VKN / PYRS	03/25/2009	Added Automotive-A information in all instances across the document.
*E	2944332	VKN	06/04/2010	<p>Added Contents Removed byte enable from footnote #2 in Electrical Characteristics Added footnote related to chip enable in Truth Table Updated Package Diagrams. Updated links in Sales, Solutions, and Legal Information.</p>

Document History Page (continued)

Document Title: CY62146EV30 MoBL®, 4-Mbit (256K × 16) Static RAM Document Number: 38-05567				
Rev.	ECN No.	Orig. of Change	Submission Date	Description of Change
*F	3109050	PRAS	12/13/2010	Changed Table Footnotes to Footnotes. Added Ordering Code Definitions .
*G	3302915	RAME	07/14/2011	Removed the references of AN1064 SRAM system guidelines from the datasheet. Updated all the notes. Updated Ordering Code Definitions . Added Units of Measure . Updated to new template.
*H	3961126	TAVA	04/10/2013	Updated Package Diagrams : spec 51-85150 – Changed revision from *F to *H. spec 51-85087 – Changed revision from *C to *E. Completing Sunset Review.
*I	4101995	VINI	08/22/2013	Updated Switching Characteristics : Updated Note 15. Updated to new template.
*J	4348752	MEMJ	04/16/2014	Updated Switching Characteristics : Added Note 19 and referred the same note in “Write Cycle” (for t _{PWE} parameter in WE controlled, OE LOW Write cycle). Updated Switching Waveforms : Added Note 28 and referred the same note in Figure 9 (for t _{PWE} parameter in WE controlled, OE LOW Write cycle). Completing Sunset Review.
*K	4576526	MEMJ	11/21/2014	Updated Functional Description : Added “For a complete list of related documentation, click here .” at the end.
*L	5233278	VINI	04/21/2016	Updated Thermal Resistance : Replaced “two-layer” with “four-layer” in “Test Conditions” column. Updated all values in “VFBGA” and “TSOP II” columns. Updated to new template. Completing Sunset Review.

Sales, Solutions, and Legal Information

Worldwide Sales and Design Support

Cypress maintains a worldwide network of offices, solution centers, manufacturer's representatives, and distributors. To find the office closest to you, visit us at [Cypress Locations](#).

Products

ARM® Cortex® Microcontrollers	cypress.com/arm
Automotive	cypress.com/automotive
Clocks & Buffers	cypress.com/clocks
Interface	cypress.com/interface
Lighting & Power Control	cypress.com/powerpsoc
Memory	cypress.com/memory
PSoC	cypress.com/psoc
Touch Sensing	cypress.com/touch
USB Controllers	cypress.com/usb
Wireless/RF	cypress.com/wireless

PSoC® Solutions

[PSoC 1](#) | [PSoC 3](#) | [PSoC 4](#) | [PSoC 5LP](#)

Cypress Developer Community

[Forums](#) | [Projects](#) | [Video](#) | [Blogs](#) | [Training](#) | [Components](#)

Technical Support

cypress.com/support

© Cypress Semiconductor Corporation, 2004-2016. This document is the property of Cypress Semiconductor Corporation and its subsidiaries, including Spansion LLC ("Cypress"). This document, including any software or firmware included or referenced in this document ("Software"), is owned by Cypress under the intellectual property laws and treaties of the United States and other countries worldwide. Cypress reserves all rights under such laws and treaties and does not, except as specifically stated in this paragraph, grant any license under its patents, copyrights, trademarks, or other intellectual property rights. If the Software is not accompanied by a license agreement and you do not otherwise have a written agreement with Cypress governing the use of the Software, then Cypress hereby grants you a personal, non-exclusive, nontransferable license (without the right to sublicense) (1) under its copyright rights in the Software (a) for Software provided in source code form, to modify and reproduce the Software solely for use with Cypress hardware products, only internally within your organization, and (b) to distribute the Software in binary code form externally to end users (either directly or indirectly through resellers and distributors), solely for use on Cypress hardware product units, and (2) under those claims of Cypress's patents that are infringed by the Software (as provided by Cypress, unmodified) to make, use, distribute, and import the Software solely for use with Cypress hardware products. Any other use, reproduction, modification, translation, or compilation of the Software is prohibited.

TO THE EXTENT PERMITTED BY APPLICABLE LAW, CYPRESS MAKES NO WARRANTY OF ANY KIND, EXPRESS OR IMPLIED, WITH REGARD TO THIS DOCUMENT OR ANY SOFTWARE OR ACCOMPANYING HARDWARE, INCLUDING, BUT NOT LIMITED TO, THE IMPLIED WARRANTIES OF MERCHANTABILITY AND FITNESS FOR A PARTICULAR PURPOSE. To the extent permitted by applicable law, Cypress reserves the right to make changes to this document without further notice. Cypress does not assume any liability arising out of the application or use of any product or circuit described in this document. Any information provided in this document, including any sample design information or programming code, is provided only for reference purposes. It is the responsibility of the user of this document to properly design, program, and test the functionality and safety of any application made of this information and any resulting product. Cypress products are not designed, intended, or authorized for use as critical components in systems designed or intended for the operation of weapons, weapons systems, nuclear installations, life-support devices or systems, other medical devices or systems (including resuscitation equipment and surgical implants), pollution control or hazardous substances management, or other uses where the failure of the device or system could cause personal injury, death, or property damage ("Unintended Uses"). A critical component is any component of a device or system whose failure to perform can be reasonably expected to cause the failure of the device or system, or to affect its safety or effectiveness. Cypress is not liable, in whole or in part, and you shall and hereby do release Cypress from any claim, damage, or other liability arising from or related to all Unintended Uses of Cypress products. You shall indemnify and hold Cypress harmless from and against all claims, costs, damages, and other liabilities, including claims for personal injury or death, arising from or related to any Unintended Uses of Cypress products.

Cypress, the Cypress logo, Spansion, the Spansion logo, and combinations thereof, PSoC, CapSense, EZ-USB, F-RAM, and Traveo are trademarks or registered trademarks of Cypress in the United States and other countries. For a more complete list of Cypress trademarks, visit cypress.com. Other names and brands may be claimed as property of their respective owners.